

SURFACE MOUNT RECTIFIERS

VOLTAGE RANGE: 50 --- 1000 V
CURRENT: 1.0 A

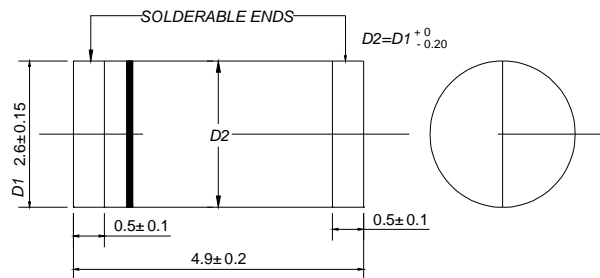
FEATURES

- ◇ Plastic package has underwriters laboratories flammability classification 94V-0
- ◇ Glass passivated chip junction
- ◇ For surface mount applications
- ◇ High temperature metallurgically bonded construction
- ◇ Cavity-free glass passivated junction
- ◇ High temperature soldering guaranteed:450 °C/5 seconds at terminals.Complete device sub-mersible temperature of 265 °C for 10 seconds in solder bath

MECHANICAL DATA

- ◇ Case: JEDEC DO-213AB,molded plastic
- ◇ Terminals: Axial lead ,solderable per MIL- STD-750,Method 2026
- ◇ Polarity: Color band denotes cathode
- ◇ Weight: 0.0046 ounces, 0.116 grams
- ◇ Mounting position: Any

DO - 213AB



Dimensions in millimeters

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase,half wave,60 Hz,resistive or inductive load. For capacitive load,derate current by 20%.

		GL 41A	GL 41B	GL 41D	GL 41G	GL 41J	GL 41K	GL 41M	GL 41T	GL 41Y	UNITS	
Maximum recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	1300	1600	V	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	910	1120	V	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	1300	1600	V	
Maximum average forward rectified current (see FIG.1)	$I_{(AV)}$	1.0									A	
Peak forward surge current 8.3ms single half-sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30									A	
Maximum instantaneous forward voltage @1.0A	V_F	1.1			1.2					V		
Maximum reverse current @ $T_A=25^\circ C$ at rated DC blocking voltage @ $T_A=125^\circ C$	I_R	10					50					μA
Typical junction capacitance (Note1)	C_j	8.0										pF
Typical thermal resistance (Note 2)	$R_{\theta JA}$	75										$^\circ C/W$
Operating junction temperature range	T_j	- 55 ---- +175									$^\circ C$	
Storage temperature range	T_{STG}	- 55 ---- +175									$^\circ C$	

NOTE: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

2. Thermal resistance from junction to ambient, 0.24×0.24"(6.0×6.0mm) copper pads to each terminal.

FIG.1 – FORWARD DERATING CURVE

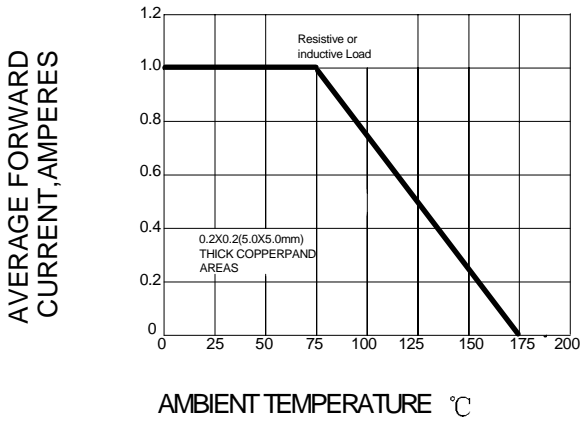


FIG.2 PEAK FORWARD SURGE CURRENT

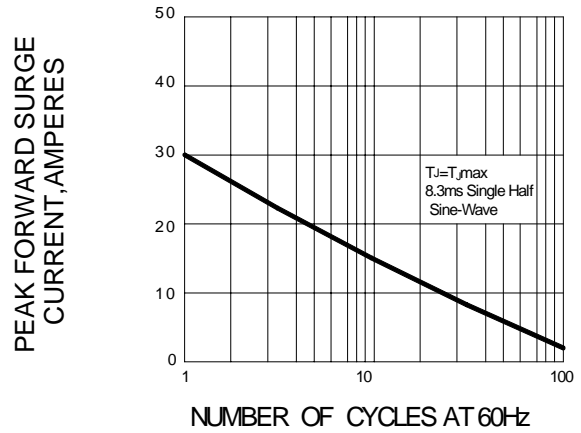


FIG.3 – TYPICAL FORWARD CHARACTERISTICS

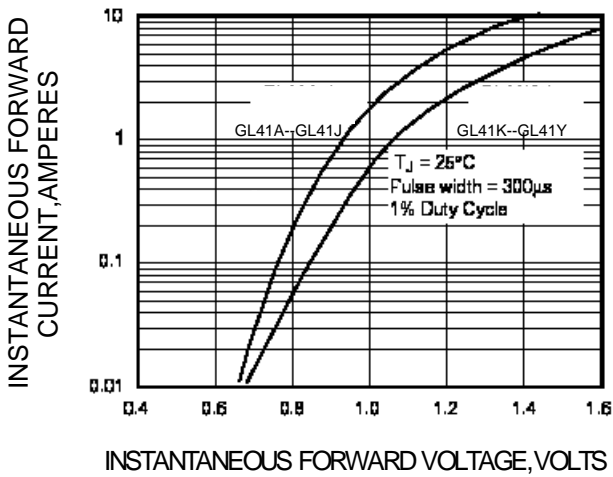


FIG.4 – TYPICAL REVERSE CHARACTERISTICS

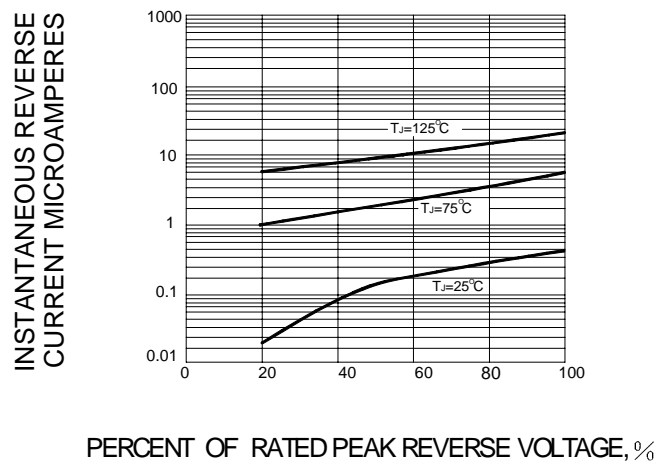


FIG.5-TYPICAL JUNCTION CAPACITANCE

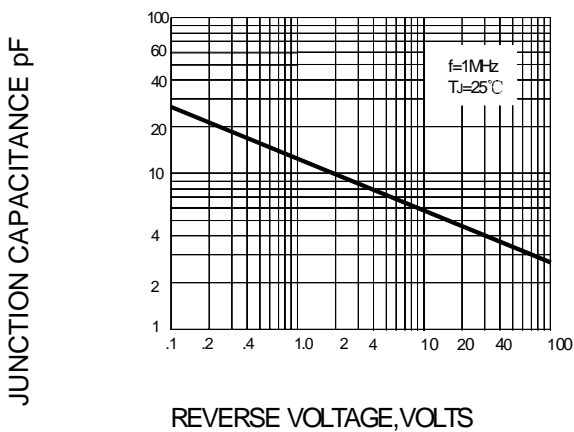


FIG.6-TRANSIENT THERMAL IMPEDANCE

